

### **REMARKS**

Applicant provides the present Amendment to address the issues raised in the Official Action mailed December 16, 2004. Applicant has amended the specification to correct a typographic error in the recitation of the claim of priority as to the year of filing. Applicant notes that the Declaration filed in the case properly recited the claim of priority and that the priority information on the filing receipt is correct.

Applicant appreciates the indication of allowable subject matter in Claims 5, 7-9 and 11-14. Applicant has amended Claims 5, 7, 8, 11, 12 and 14 to write these claims in independent form. Applicant has amended Claim 13 to depend from Claim 12. Accordingly, Applicant submits that Claims 5, 7-9 and 11-14 are in condition for allowance.

Applicant has also amended Claim 1 to recite that dynamically adjusting the saw cut pattern is provide by "adjusting where in a path of the saw for a first saw cut across the semiconductor wafer the saw proceeds to a next saw cut across the semiconductor wafer." Support for this amendment is provided, for example, in the Figures and at page 9, lines 10-13 of the present Specification.

### **The Anticipation Rejections**

Claims 1, 15 and 16 stand rejected as anticipated under 35 U.S.C. § 102(b) by United States Patent No. 6,165,051 to WeissHaus *et al.* (hereinafter "WeissHaus"). Official Action, p. 2. As noted above, Claim 1 has been amended to recite that the manner in which the saw cut pattern is adjusted is by adjusting where in a path of the saw for a first saw cut across the semiconductor wafer the saw proceeds to a next saw cut across the semiconductor wafer.

The Official Action cites to col. 3, lines 14-17 of WeissHaus as disclosing the recitations of Claim 1. Official Action, pp. 2-3. However, this portion of WeissHaus does not disclose or suggest the dynamic adjustment of where in the path of a saw cut across a wafer the saw proceeds to a next saw cut. Merely adjusting the speed of the spindle, the feed rate of the substrate, the cutting depth or the coolant feed rate does not necessarily adjust where in a path of a first saw cut across a wafer the saw proceeds to a next saw cut. Furthermore, while WeissHaus does appear to state at

least in col. 6 that the load on the blade may be used to detect the end of the wafer, there does not appear to be a disclosure or suggestion that where in a first saw cut the saw proceeds to a next saw cut is dynamically adjusted as recited in amended Claim 1. Accordingly, Applicant submits that amended Claim 1 is not anticipated by the cited portions of Weisshaus.

With regard to Claims 15 and 16, Applicant submits that these claims are patentable at least as depending from a patentable base claim. Applicant also notes that the portion of Weisshaus cited as disclosing the recitations of Claim 15 recites that the wafer is silicon, not silicon carbide as recited in Claim 15.

Claims 1 and 10 stand rejected as anticipated under 35 U.S.C. § 102(b) by United States Patent No. 5,668,061 to Herko et al. (hereinafter "Herko"). The Official Action cites to the alignment of the saw with fiducial marks as discussed in Herko in rejecting Claim 1. Official Action, p. 3. Applicant submits that the alignment of the saw with fiducial marks does not disclose or suggest dynamically changing where in a path of a first saw cut across a wafer the saw proceeds to a next saw cut across the wafer as is recited in amended Claim 1. As such, Applicant submits that amended Claim 1 is not anticipated by the cited portions of Herko for at least these reasons. Applicant submits that Claim 10 is patentable at least as depending from a patentable base claim.

Claim 1 stands rejected as anticipated under 35 U.S.C. § 102(e) by United States Patent Publication No. 2001/0032533 to Sekiya (hereinafter "Sekiya"). In particular, the Official Action cites to paragraphs 43-44 and 48-51 of Sekiya as disclosing the recitations of Claim 1. Official Action, p. 4. These paragraphs appear to describe alignment of a wafer with a saw (paragraphs 43-44) and imaging the wafer and the aligning the wafer to detect a first street cut (paragraphs 48-50). The streets are then cut by indexing the saw to a next cut (paragraph 51). Thus, it does not appear that the cited portions of Sekiya dynamically adjust where in a path of a first saw cut across a wafer a saw proceeds to a next saw cut across the wafer as recited in amended Claim 1. Accordingly, Applicant submits that amended Claim 1 is not anticipated by Sekiya for at least these reasons.

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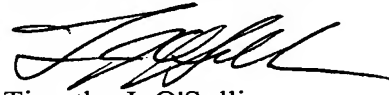
**The Obviousness Rejections**

Claims 2, 3, 4 and 6 stand rejected as obvious under 35 U.S.C. § 103 in light of the combination of Sekiya and JP 63319110 A to Sakai (hereinafter "Sakai"). Applicant submits that these claims are patentable at least as depending from a patentable base claim.

**Conclusion**

In light of the above discussion, Applicant submits that the present application is in condition for allowance, which action is respectfully requested.

Respectfully submitted,



Timothy J. O'Sullivan  
Registration No. 35,632

Myers Bigel Sibley & Sajovec, P.A.  
P. O. Box 37428  
Raleigh, North Carolina 27627  
Telephone: (919) 854-1400  
Facsimile: (919) 854-1401  
Customer No. 20792

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Traci A. Brown Date of Signature: March 2, 2005